



# 20V P-CHANNEL ENHANCEMENT MODE MOSFET POWERDI

#### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub>	I <sub>D</sub> T <sub>C</sub> = +25°C
	$1.9 m\Omega @ V_{GS} = -10V$	-60A
-20V	$2.4 m\Omega$ @ $V_{GS} = -4.5 V$	-60A
	$3.8 \text{m}\Omega$ @ $V_{GS} = -2.5 \text{V}$	-60A

#### **Description**

This new generation P-Channel Enhancement Mode MOSFET is designed to minimize  $R_{DS(ON)}$  and yet maintain superior switching performance. This device is ideal for use in notebook battery power management and load switch.

#### **Applications**

Switch

PowerDI5060-8 (Type K)





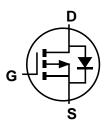


#### **Features**

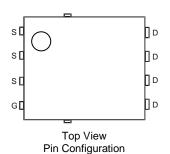
- Thermally Efficient Package-Cooler Running Applications
- High Conversion Efficiency
- Low R<sub>DS(ON)</sub> Minimizes On State Losses
- <1.1mm Package Profile Ideal for Thin Applications</li>
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

- Case: PowerDI5060-8 (Type K)
- Case Material: Molded Plastic, "Green" Molding Compound;
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe;
   Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.097 grams (Approximate)



Internal Schematic



#### Ordering Information (Note 4)

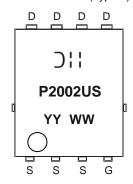
Part Number	Case	Packaging
DMP2002UPS-13	PowerDI5060-8 (Type K)	2,500 / Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### **Marking Information**

PowerDI5060-8 (Type K)



☐ Hanufacturer's Marking
P2002US = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 16 = 2016)
WW = Week Code (01 to 53)



## **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage	V <sub>DSS</sub>	-20	V		
Gate-Source Voltage	V <sub>GSS</sub>	±12	V		
Outliness Proje Outlines IV 40V/Note 5	Steady State (Note 8)	$T_{C} = +25^{\circ}C$ $T_{C} = +70^{\circ}C$		-60 -60	А
Continuous Drain Current, V <sub>GS</sub> = -10V (Note 5)	t<10s	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	-42 -33.5	А
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I <sub>DM</sub>	-100	Α		
Continuous Body Diode Forward Current (Note 5)	Steady State (Note 8)	T <sub>C</sub> = +25°C	Is	-60	А
, , , , , , , , , , , , , , , , , , , ,	t<10s	$T_A = +25$ °C		-5.6	А
Pulsed Body Diode Forward Current (10µs pulse, duty cy	I <sub>SM</sub>	-100	Α		
Avalanche Current, L = 0.1mH			I <sub>AS</sub>	-37	Α
Avalanche Energy, L = 0.1mH			E <sub>AS</sub>	69.8	mJ

### **Thermal Characteristics**

Characteristic	Symbol	Value	Units	
Total Dawar Dissination (Note E)	Steady State		2.3	W
Total Power Dissipation (Note 5)	t<10s	$P_D$	6.25	
Thermal Desistance Junction to Ambient (Note 5)	Steady State	D	55	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	20	
Total Power Dissipation (Note 5)	Steady State	P <sub>D</sub>	104	W
Thermal Resistance, Junction to Case (Note 5)		R <sub>0JC</sub>	0.9	°C/W
Operating and Storage Temperature Range	T <sub>J,</sub> T <sub>STG</sub>	-55 to +150	°C	



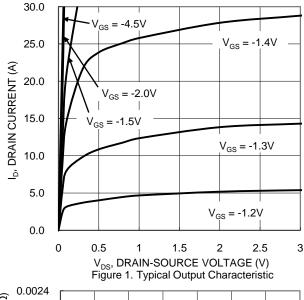
#### **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

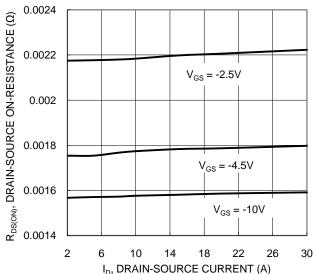
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 6)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-20	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	-1	μΑ	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 6)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-0.5	1	-1.4	٧	$V_{DS} = V_{GS}$ , $I_D = -250\mu A$	
		1	1.3	1.9	mΩ	V <sub>GS</sub> = -10V, I <sub>D</sub> = -25A	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	1	1.5	2.4		$V_{GS} = -4.5V$ , $I_{D} = -20A$	
		1	2	3.8		$V_{GS} = -2.5V, I_D = -15A$	
DYNAMIC CHARACTERISTICS (Note 7)							
Input Capacitance	C <sub>iss</sub>	1	12826	_			
Output Capacitance	Coss	1	2547	_	pF	$V_{DS} = -10V$ , $V_{GS} = 0V$ f = 1MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>	1	1924	_		1 - 111112	
Gate Resistance	R <sub>G</sub>	0.9	4.2	6.6	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = -10V)	Qg	1	476	585			
Total Gate Charge (V <sub>GS</sub> = -4.5V)	Qg	1	228	282	nC	V <sub>DS</sub> = -10V, I <sub>D</sub> = -20A	
Gate-Source Charge	Q <sub>gs</sub>	1	24.8	_	110		
Gate-Drain Charge	$Q_{gd}$	1	61.9	_			
Turn-On Delay Time	t <sub>D(ON)</sub>	_	14.2	28			
Turn-On Rise Time	t <sub>R</sub>	_	35.4	70		$V_{DD} = -10V, V_{GEN} = -4.5V,$	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	361	578	ns	$R_{GEN} = 1\Omega$ , $I_D = -10A$	
Turn-Off Fall Time	t <sub>F</sub>	_	224	358			
BODY DIODE CHARACTERISTICS							
Continuous Body Diode Forward Current (Notes 5 & 8)	Is	_	_	-60	Α	$T_C = +25^{\circ}C$	
Diode Forward Voltage	$V_{SD}$	_	-0.58	-1.1	V	$V_{GS} = 0V, I_{S} = -5A$	
Reverse Recovery Time (Note 7)	t <sub>RR</sub>	_	137	219	ns		
Reverse Recovery Charge (Note 7)	Q <sub>RR</sub>	1	221	332	nC		
Reverse Recovery Fall Time (Note 7)	t <sub>A</sub>		39		200	I <sub>F</sub> = -10A, di/dt = 100A/μs	
Reverse Recovery Raise Time (Note 7)	t <sub>B</sub>	_	98	_	ns		

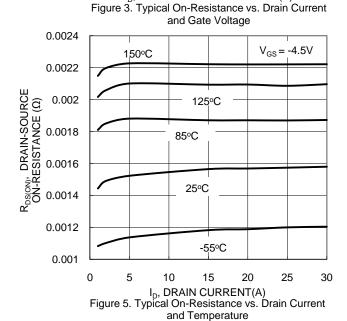
Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.
 Package limited.

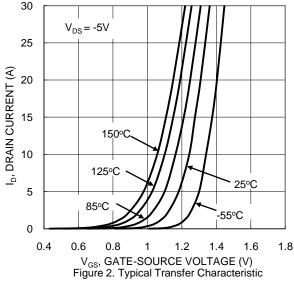


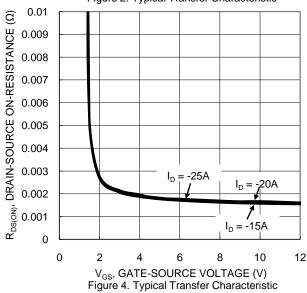


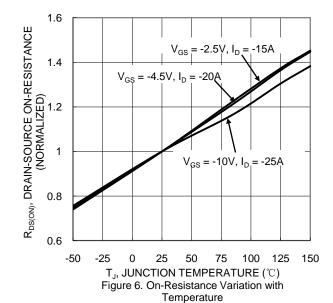






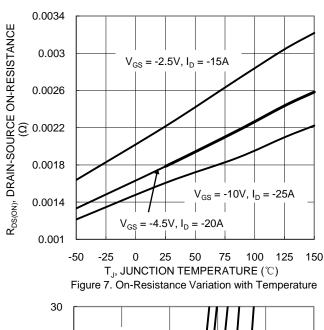


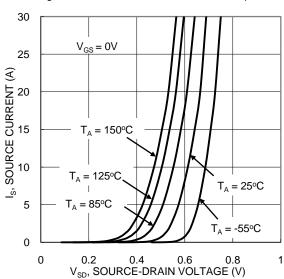


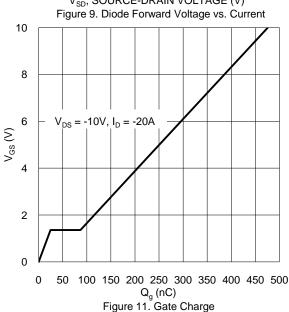


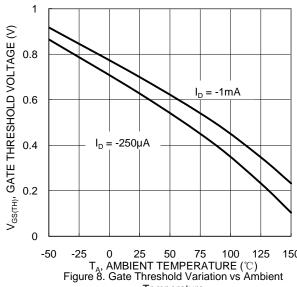


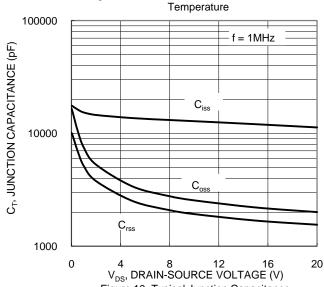


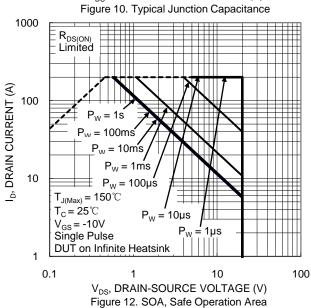














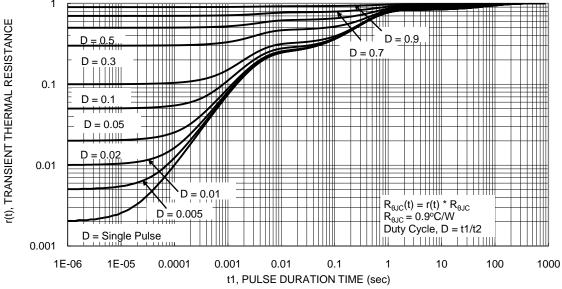


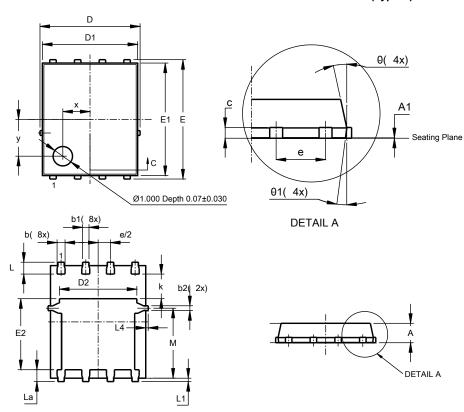
Figure 13. Transient Thermal Resistance



### **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI5060-8 (Type K)

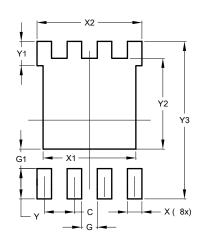


PowerDI5060-8 (Type K)					
Dim	Min	Max	Тур		
Α	0.90	1.10	1.00		
A1	0	0.05	0.02		
b	0.33	0.51	0.41		
b1	0.300	0.366	0.333		
b2	0.20	0.35	0.25		
С	0.23	0.33	0.277		
D	5	.15 BS0	)		
D1	4.85	4.95	4.90		
D2	-	-	3.98		
Е	6	.15 BS0			
E1	5.75	5.85	5.80		
E2	3.56	3.725	3.66		
Е	1	.27BSC	)		
k	-	-	1.27		
L	0.51	0.71	0.61		
La	0.51	0.675	0.61		
L1	0.05	0.20	0.175		
L4	-	-	0.125		
M	3.50	3.71	3.605		
X	-	-	1.400		
У	-	-	1.900		
θ	10°	12°	11°		
θ1	6°	8°	7°		
All Dimensions in mm					

### **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI5060-8 (Type K)



Dimensions	Value (in mm)		
С	1.270		
G	0.660		
G1	0.820		
Х	0.610		
X1	3.910		
X2	4.420		
Y	1.270		
Y1	1.020		
Y2	3.810		
Y3	6.610		



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